

SurgX® ESD Suppressors

Surface Mount Transient Voltage Suppressors

SOT23ESD-A

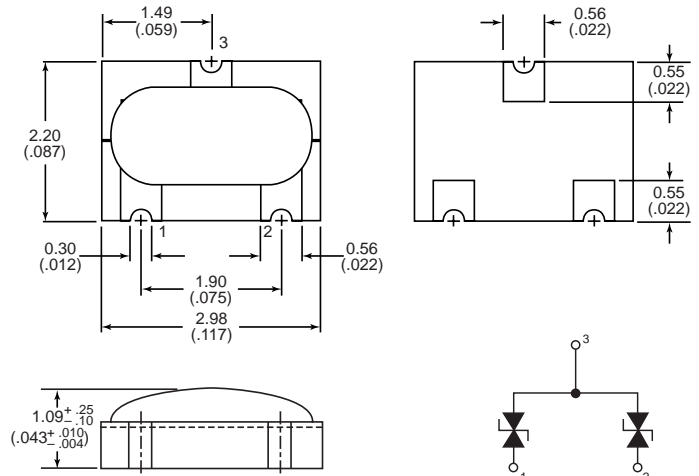
A Unique Approach to ESD Protection

SurgX® suppressors by Bussmann provide electrostatic discharge (ESD) protection in mobile communications, data processing, and many other electronic applications. They are ideally suited for low voltage, high data rate micro-processor-based circuits. The SurgX products utilize unique polymer-based materials for the suppression of the fast transient voltages caused by ESD, in conformance with IEC 61000-4-2 and MIL-STD-883C.

Features:

- Ultra-low Capacitance & Leakage Current
- Fast Response Time
- Withstands up to 15kV @ 45A ESD Pulse
- Bidirectional

Dimensional Data



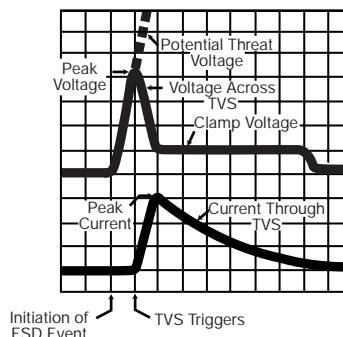
Electrical Characteristics

Continuous Operating Voltage	24V maximum
Clamping Voltage ^{1,2}	40V typical, 60V maximum
Peak Voltage ¹	150V typical, 300V maximum
Capacitance ³	1pF typical
Leakage Current ⁴	100nA max
Peak Current ^{1,2}	30A maximum
ESD Withstand ¹	20 pulses minimum

Notes:

1. Per IEC 61000-4-2, 30A @ 8kV, contact discharge.
2. Measurement made 30nS after initiation of pulse.
3. Measured @ 1MHz.
4. Measured at 24 Vdc.

Typical Transient Response



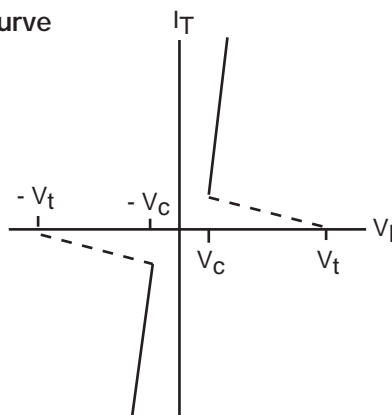
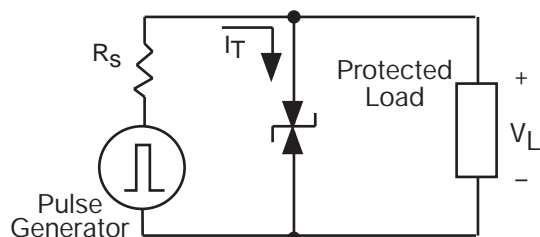
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Typical Circuit and Generalized V-I Curve

V_t = Trigger Voltage
 V_c = Clamping Voltage



Packaging Information:

- Tape and Reel: Standard 8mm tape, in compliance with EIA-RS481 (equivalent to IEC 286, Part 3).
- Code: **TR1** = 2,000 pieces on tape on a 178mm reel.
SP1 = 10 pieces on tape in a plastic box.

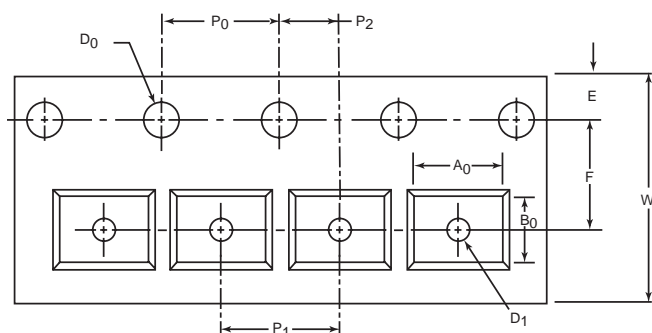
EX: TR1/SOT23ESD-A denotes 2,000 pieces on tape.

Mechanical Specifications:

- Substrate: Ceramic
- End termination finish: Nickel barrier (3.88 – 4.3µm), followed by 90/10 tin – lead (5.1 – 10.2µm)
- ESD barrier: SurgX polymeric material

Environmental Specifications:

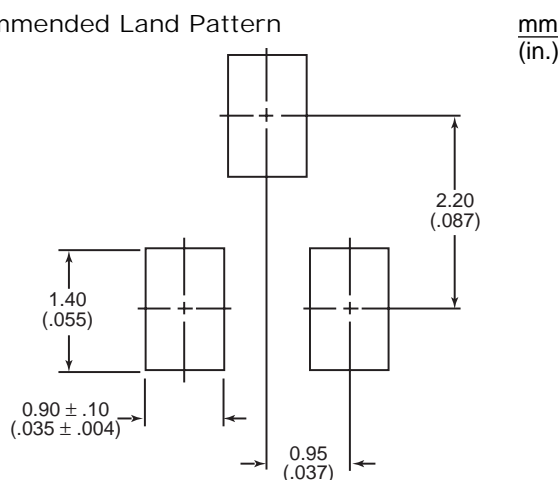
- Dry heat: 96 hours @ 85°C
- Humidity: 96 hours @ 85% RH, 60°C
- Thermal shock: –55°C to 85°C, 1 hour cycle, 10 cycles
- Vibration: MIL-STD202, Method 204, Test Condition C, (55 to 2000 Hz, 10Gs)
- Solderability: withstands 60 seconds above 200°C, 260°C maximum
- Solder leach resistance and terminal adhesion per EIA-576



Carrier Dimensions – mm (in.)

W	8.0 ± 0.1 (.315 ± .004)
F	3.5 ± 0.05 (.138 ± .002)
E	1.75 ± 0.1 (.069 ± .004)
P2	2.0 ± 0.05 (.079 ± .002)
P0	4.0 ± 0.1 (.157 ± .004)
P1	4.0 ± 0.1 (.157 ± .004)
A0	3.20 ± 0.1 (.126 ± .004)
B0	2.44 ± 0.1 (.096 ± .004)
D0	1.5 + 0.1 / -0.0 (.059 + .004 / -.000)
D1	1.00 ± .25 (.039 ± .001)

Recommended Land Pattern



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